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# Automotive P-Channel 30 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	-30				
$R_{DS(on)}(\Omega)$ at $V_{GS} = -10 \text{ V}$	0.0085				
$R_{DS(on)}(\Omega)$ at $V_{GS} = -4.5 \text{ V}$	0.0200				
I <sub>D</sub> (A)	-22				
Configuration	Single				



#### **FEATURES**

• TrenchFET® power MOSFET

• AEC-Q101 qualified

• ESD Protection: 3000 V

• 100 % UIS tested

 Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



ROHS COMPLIANT HALOGEN FREE

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G 52	100 Ω	
	P-Channel	D

ORDERING INFORMATION	
Package	SO-8
Lead (Pb)-free and Halogen-free	SQ4483BEEY-T1-GE3

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		$V_{DS}$	-30	V	
Gate-Source Voltage		$V_{GS}$	± 20	V	
Continuous Drain Current	T <sub>C</sub> = 25 °C	I <sub>D</sub>	-22		
	T <sub>C</sub> = 125 °C		-13		
Continuous Source Current (Diode Conduction)		I <sub>S</sub>	-6	Α	
Pulsed Drain Current <sup>a</sup>		I <sub>DM</sub>	-84		
Single Pulse Avalanche Current	L = 10 mH	I <sub>AS</sub>	-7		
Single Pulse Avalanche Energy	L = 10 IIIH	E <sub>AS</sub>	245	mJ	
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C	P <sub>D</sub>	7	W	
	T <sub>C</sub> = 125 °C	l D	2	VV	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient F	PCB Mount b	$R_{thJA}$	85	°C/W	
Junction-to-Foot (Drain)		$R_{thJF}$	21	C/VV	

#### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. When mounted on 1" square PCB (FR4 material).



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PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		-30	-	-	V
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$		-2.0	-2.5	v
Gate-Source Leakage	1	V <sub>DS</sub> =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 1	mA
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$		-	± 2	
Zero Gate Voltage Drain Current		$V_{GS} = 0 V$	V <sub>DS</sub> = -30 V	1	-	-1	μΑ
	I <sub>DSS</sub>	$V_{GS} = 0 V$	$V_{DS} = -30 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$	ı	-	-50	
		$V_{GS} = 0 V$	$V_{DS} = -30 \text{ V}, T_{J} = 175 ^{\circ}\text{C}$	ì	-	-150	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = -10 V	$V_{DS} \le -5 \text{ V}$	-30	-	-	Α
Drain-Source On-State Resistance <sup>a</sup>		V <sub>GS</sub> = -10 V	I <sub>D</sub> = -10 A	-	0.0070	0.0085	Ω
	Ь	V <sub>GS</sub> = -10 V	I <sub>D</sub> = -10 A, T <sub>J</sub> = 125 °C	=	-	0.0130	
	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10 V	I <sub>D</sub> = -10 A, T <sub>J</sub> = 175 °C	=	-	0.0150	
		$V_{GS} = -4.5 \text{ V}$	I <sub>D</sub> = -7 A	-	0.0160	0.0200	
Forward Transconductance b	9 <sub>fs</sub>	V <sub>DS</sub> =	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -10 A		32	-	S
Dynamic <sup>b</sup>							
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = -15 V, f = 1 MHz	-	712	890	рF
Total Gate Charge <sup>c</sup>	Qg			=	75	113	nC
Gate-Source Charge c	$Q_{gs}$	$V_{GS} = -10 \text{ V}$	$V_{DS} = -15 \text{ V}, I_{D} = -10 \text{ A}$	ì	9.5	-	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$				19	-	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>		$V_{DD}$ = -15 V, $R_L$ = 1.5 $\Omega$ $I_D \cong$ -10 A, $V_{GEN}$ = -10 V, $R_g$ = 1 $\Omega$		38	57	
Rise Time <sup>c</sup>	t <sub>r</sub>	V <sub>DD</sub> =			82	123	- μs
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong -10 A$ ,			134	201	
Fall Time <sup>c</sup>	t <sub>f</sub>	1		=	178	214	
Source-Drain Diode Ratings and Chara	acteristics <sup>b</sup>						
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	-84	Α
Forward Voltage	$V_{SD}$	I <sub>F</sub> = -3 A, V <sub>GS</sub> = 0 V		_	-0.75	-1.2	V

### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

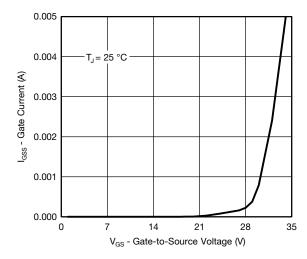
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

10-2

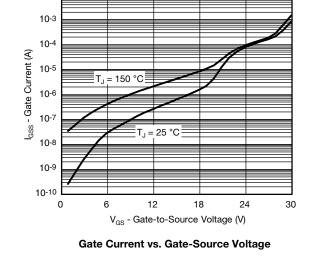


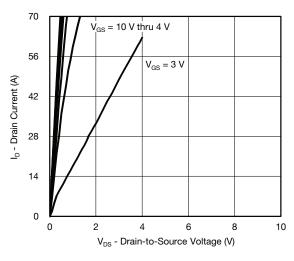
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## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

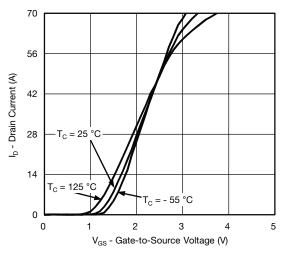


#### Gate Current vs. Gate-Source Voltage

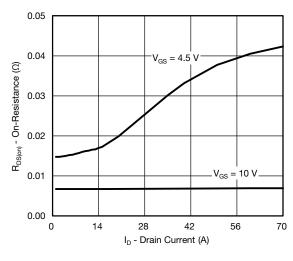




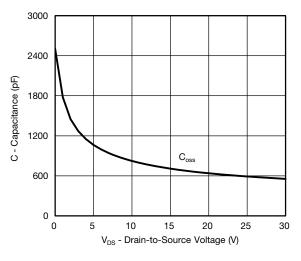
**Output Characteristics** 



Transfer Characteristics



On-Resistance vs. Drain Current

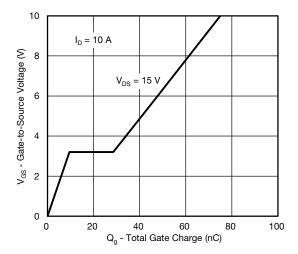


Capacitance

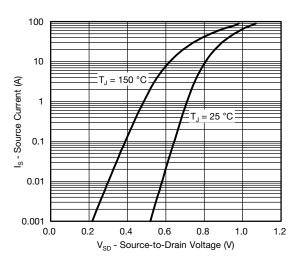


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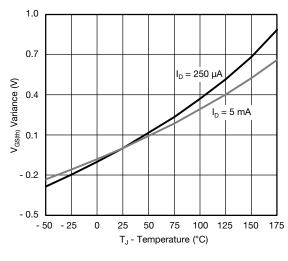
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



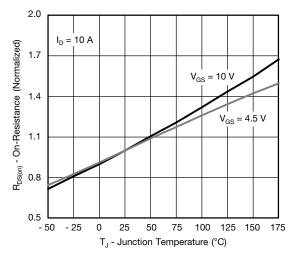
#### **Gate Charge**



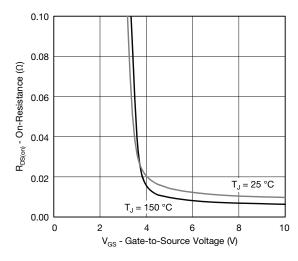
#### **Source Drain Diode Forward Voltage**



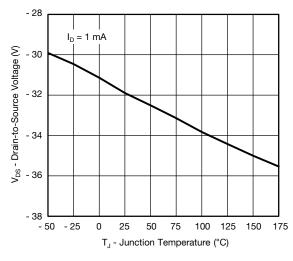
**Threshold Voltage** 



On-Resistance vs. Junction Temperature



On-Resistance vs. Gate-to-Source Voltage

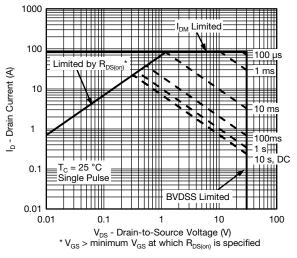


Drain Source Breakdown vs. Junction Temperature

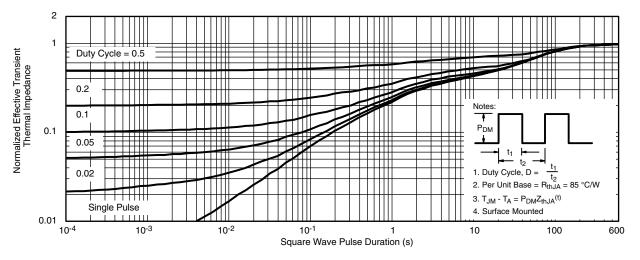
For technical questions, contact: automostechsu

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## **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



#### **Safe Operating Area**



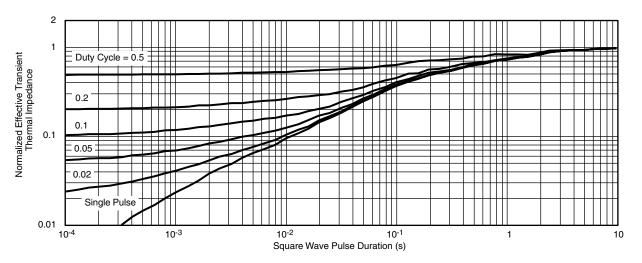
Normalized Thermal Transient Impedance, Junction-to-Ambient



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## **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



#### Normalized Thermal Transient Impedance, Junction-to-Foot

#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Foot (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg267097">www.vishay.com/ppg267097</a>.



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